



FMS6363 — Low-Cost, Three-Channel, 6th-Order, High-Definition, Video Filter Driver

Features

- Three Sixth-order 30MHz (HD) Filters
- Transparent Input Clamping
- Single Video Drive Load ($2V_{pp}$, $150\Omega = 6\delta\beta$)
- AC or DC-coupled Inputs
- AC or DC-coupled Outputs
- DC-coupled Outputs Eliminate AC-coupling Capacitors
- 5V Only
- Robust 8kV ESD Protection
- Package SOIC-8

Description

The FMS6363 low-cost video filter (LCVF) is intended to replace passive LC filters and drivers with a low-cost integrated device. Three sixth-order filters provide improved image quality compared to typical lower-order passive solutions.

The FMS6363 may be directly driven by a DC-coupled DAC output or an AC-coupled signal. Internal diode clamps and bias circuitry may be used if AC-coupled inputs are required (*see Applications section for details*).

The outputs can drive AC-or DC-coupled single (150Ω) loads. DC-coupling the outputs removes the need for output coupling capacitors. The input DC levels are offset approximately +280mV at the output (*see Applications section for details*).

Applications

- Cable and Satellite Set-top Boxes
- DVD Players
- HDTV
- Personal Video Recorders (PVR)
- Video On Demand (VOD)

Block Diagram

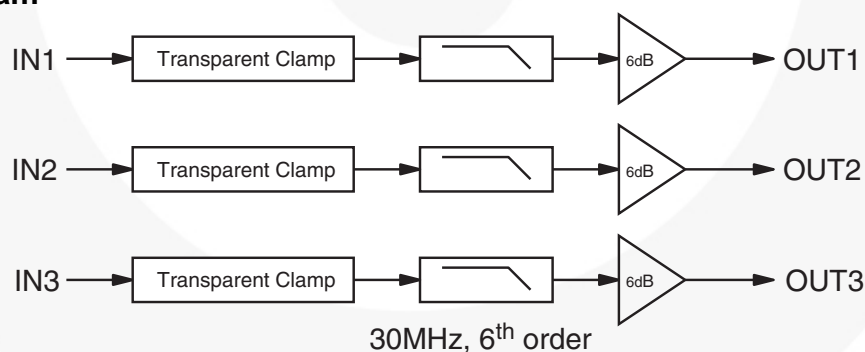


Figure 1. Block Diagram

Ordering Information

Part Number	Operating Temperature Range	Package	Packing Method	Quantity
FMS6363CS	0 to 70°C	8-Lead, Small Outline Integrated Circuit (SOIC)	Rail	95
FMS6363CSX	0 to 70°C	8-Lead, Small Outline Integrated Circuit (SOIC)	Reel	2500

All packages are lead free per JEDEC: J-STD-020B standard.

Pin Configuration

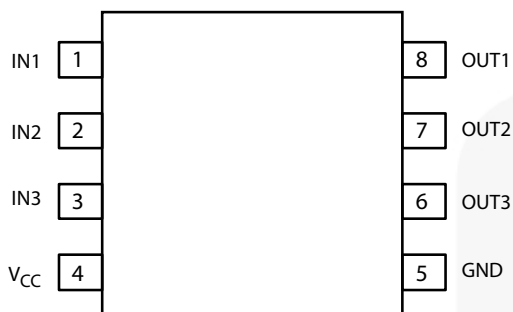


Figure 2. 8-Pin SOIC

Pin Definitions

Pin #	Name	Type	Description
1	IN1	Input	Video input, channel 1
2	IN2	Input	Video input, channel 2
3	IN3	Input	Video input, channel 3
4	V _{CC}	Input	+5V Supply
5	GND	Input	Ground
6	OUT3	Output	Filtered output, channel 3
7	OUT2	Output	Filtered output, channel 2
8	OUT1	Output	Filtered output, channel 1

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Min.	Max.	Unit
V _{CC}	DC Supply Voltage	-0.3	6.0	V
V _{IO}	Analog Digital I/O	-0.3	V _{CC} + 0.3	V
I _{OUT}	Output Current, Any One Channel, Do Not Exceed		50	mA
ESD	Human Body Model, JESD22-A114		8	kV

Reliability Information

Symbol	Parameter	Min.	Typ.	Max.	Unit
T _J	Junction Temperature			+150	°C
T _{STG}	Storage Temperature Range	-65		+150	°C
T _L	Lead Temperature, Soldering 10 Seconds			+300	°C
□ _{JA}	Thermal Resistance, JEDEC Standard, Multi-layer Test Board, Still Air		112.7		°C/W

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Typ.	Max.	Unit
T _A	Operating Temperature Range	0		70	°C
V _{CC}	Supply Voltage Range	4.75	5.00	5.25	V
R _{SOURCE}	Input Source Resistance			300	Ω

DC Electrical Characteristics

$T_A=25^{\circ}\text{C}$, $V_{CC}=5\text{V}$, $R_{SOURCE}=37.5\Omega$, inputs AC coupled with $0.1\mu\text{F}$, all outputs AC coupled with $220\mu\text{F}$ into 150Ω loads, referenced to 400kHz ; unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
I_{CC}	Supply Current ⁽¹⁾	No Load		22	30	mA
V_{IN}	Video Input Voltage Range	Referenced to GND, if DC-coupled		1.4		V_{PP}

Note:

- 100% tested at 25°C .

AC Electrical Characteristics

$T_A=25^{\circ}\text{C}$, $V_{IN}=1V_{PP}$, $V_{CC}=5\text{V}$, $R_{SOURCE}=37.5\Omega$, inputs AC coupled with $0.1\mu\text{F}$, all outputs AC coupled with $220\mu\text{F}$ into 150Ω loads, referenced to 400kHz ; unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
AV	Channel Gain ⁽²⁾	All Channels	5.8	6.0	6.2	dB
f_{1dB}	-1dB Bandwidth ⁽²⁾	All Channels	23	30		MHz
f_C	-3dB Bandwidth	All Channels	30	33		MHz
f_{SB1}	Attenuation, Stopband Reject	All Channels at $f=37.125\text{MHz}$		6.5		dB
f_{SB2}		All Channels at $f=44.25\text{MHz}$		14.5		
f_{SB3}		All Channels at $f=74.25\text{MHz}$ ⁽²⁾	32	36		
THD1	Output Distortion, All Channels ⁽³⁾	$V_{OUT}=1.4V_{PP}$, 10MHz		0.2		%
THD2		$V_{OUT}=1.4V_{PP}$, 15MHz		0.4		
THD3		$V_{OUT}=1.4V_{PP}$, 22MHz		1.2		
X_{TALK}	Crosstalk Channel-to-Channel	At 1MHz		-60		dB
SNR1 SNR2	Signal-to-Noise Ratio, All Channels ⁽⁴⁾	Unweighed; 30MHz lowpass, 100kHz to 30kHz		65		dB
t_{pd}	Propagation Delay	Delay from input to output		20		ns

Notes:

- 100% tested at 25°C .
- $1.4V_{PP}$ active video.
- $\text{SNR}=20 \cdot \log(714\text{mV/rms noise})$.

Typical Performance Characteristics

$T_A=25^{\circ}\text{C}$, $V_{CC}=5\text{V}$, $R_{SOURCE}=37.5\Omega$, inputs AC coupled with $0.1\mu\text{F}$, all outputs AC coupled with $220\mu\text{F}$ into 150Ω loads, referred to 400kHz ; unless otherwise noted.

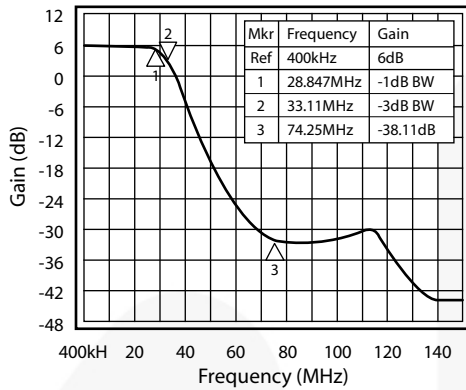


Figure 3. Frequency Response

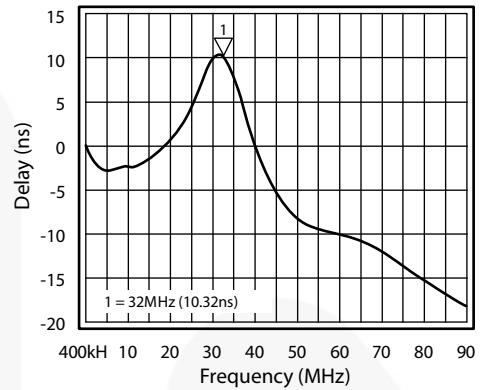


Figure 4. Group Delay vs. Frequency

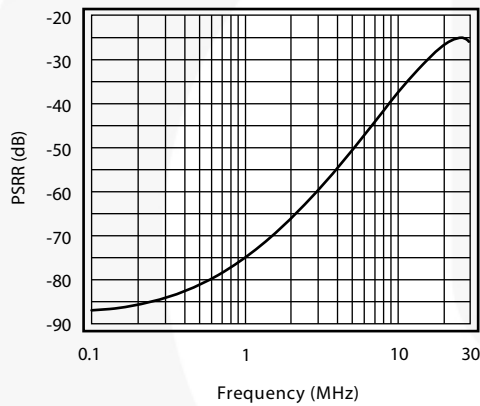


Figure 5. PSRR vs. Frequency; No Bypass Caps

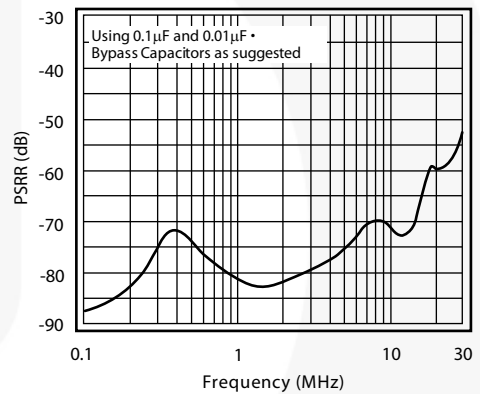


Figure 6. PSRR vs. Frequency; Bypass Caps

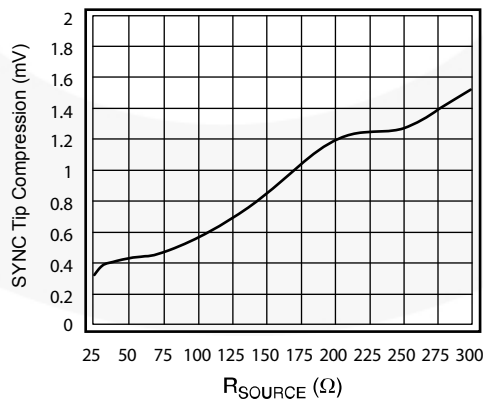


Figure 7. SYNC Tip Compression vs. R_{SOURCE}

Applications Information

Functional Description

The FMS6363 Low-Cost Video Filter (LCVF) provides 6dB gain from input to output. In addition, the input is slightly offset to optimize the output driver performance. The offset is held to the minimum required value to decrease the standing DC current into the load. Typical voltage levels are shown in Figure 8.

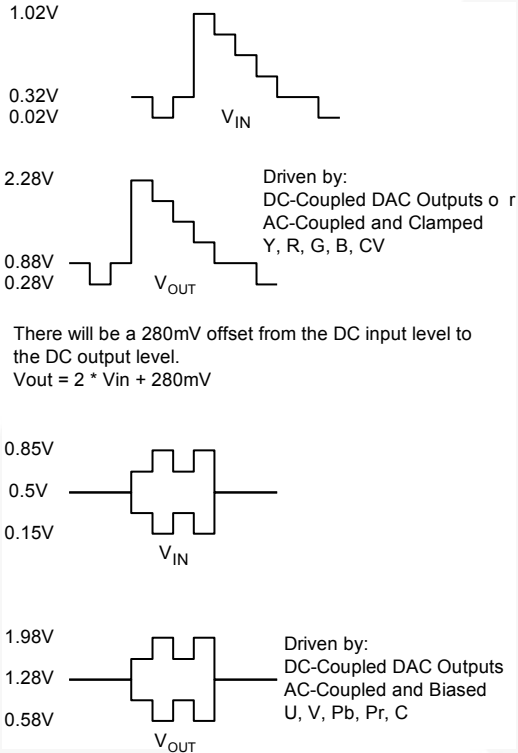


Figure 8. Typical Voltage Levels

The FMS6363 provides an internal diode clamp to support AC coupled input signals. If the input signal does not go below ground, the input clamp does not operate. This allows DAC outputs to directly drive the FMS6363 without an AC coupling capacitor. The worst-case sync tip compression due to the clamp does not exceed 7mV. The input level set by the clamp, combined with the internal DC offset, keeps the output within its acceptable range. When the input is AC-coupled, the diode clamp sets the sync tip (or lowest voltage) just below ground.

For symmetric signals like C, U, V, Cb, Cr, Pb and Pr; the average DC bias is fairly constant and the inputs can be AC-coupled with the addition of a pull-up resistor to set the DC input voltage. DAC outputs can also drive these same signals without the AC coupling capacitor. A conceptual illustration of the input clamp circuit is shown in Figure 9.

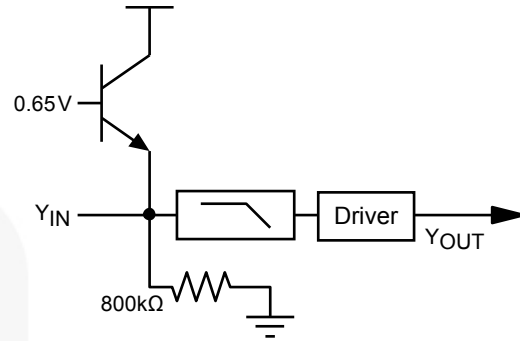


Figure 9. Input Clamp Circuit

I/O Configurations

For DC-coupled DAC drive with DC-coupled outputs, use the configuration in Figure 10.

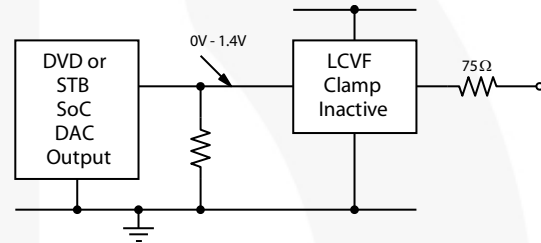


Figure 10. DC-coupled Inputs and Outputs

Alternatively, if the DAC's average DC output level causes the signal to exceed the range of 0V to 1.4V, it can be AC-coupled, as shown in Figure 11.

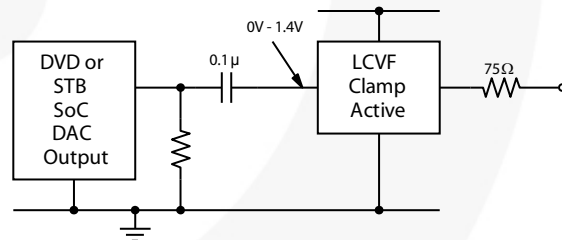


Figure 11. AC-coupled Inputs, DC-coupled Outputs

When the FMS6363 is driven by an unknown external source or a SCART with its own clamping circuitry the inputs should be AC-coupled, shown in Figure 12.

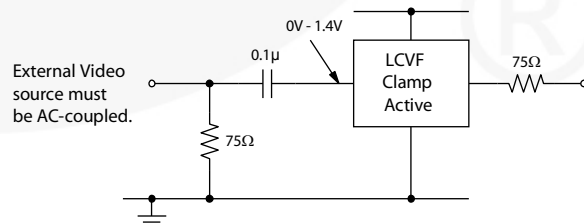


Figure 12. SCART with DC-coupled Outputs

The same method can be used for biased signals with the addition of a pull-up resistor to make sure the clamp never operates. The internal pull-down resistance is $800\text{k}\Omega \pm 20\%$, so the external resistance should be $7.5\text{M}\Omega$ to set the DC level to 500mV . If a pull-up resistance of less than $7.5\text{M}\Omega$ is desired, add an external pull-down such that the DC input level is set to 500mV .

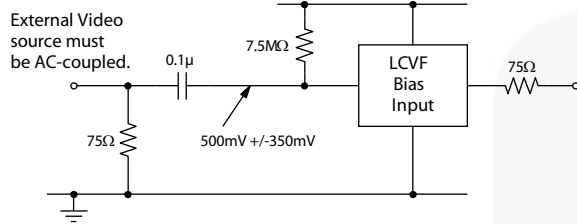


Figure 13. Biased SCART with DC-coupled Outputs

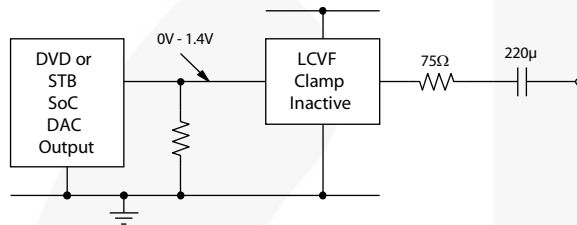


Figure 14. DC-coupled Inputs, AC-coupled Outputs

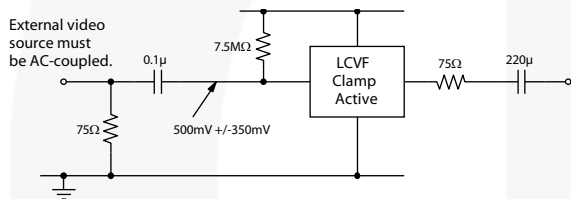


Figure 15. Biased SCART with AC-Coupled Outputs

Note: The video tilt or line time distortion is dominated by the AC-coupling capacitor. The value may need to be increased beyond $220\mu\text{F}$ to obtain satisfactory operation in some applications.

Power Dissipation

The FMS6363 output drive configuration must be considered when calculating overall power dissipation. Care must be taken not to exceed the maximum die junction temperature. The following example can be used to calculate the FMS6363's power dissipation and internal temperature rise.

$$T_J = T_A + P_d \cdot \Theta_{JA} \quad (1)$$

where $P_d = P_{CH1} + P_{CH2} + P_{CH3}$

and $P_{CHx} = V_S \cdot I_{CH} - (V_O^2/R_L)$

where

$$V_O = 2V_{IN} + 0.280\text{V}$$

$$I_{CH} = (I_{CC}/3) + (V_O/R_L)$$

V_{IN} = RMS value of input signal

$$I_{CC} = 24\text{mA}$$

$$V_S = 5\text{V}$$

R_L = channel load resistance

Board layout affects thermal characteristics. Refer to the *Layout Considerations* section for more information.

The FMS6363 is specified to operate with output currents typically less than 50mA , more than sufficient for a single (150Ω) video load. Internal amplifiers are current limited to a maximum of 100mA and should withstand brief duration, short-circuit conditions; however, this capability is not guaranteed.

Layout Considerations

Layout and supply bypassing play major roles in high-frequency performance and thermal characteristics.

For optimum results, follow the steps below as a basis for high-frequency layout:

- Include $10\mu\text{F}$ and $0.1\mu\text{F}$ ceramic bypass capacitors
- Place the $10\mu\text{F}$ capacitor within 0.75 inches of the power pin.
- Place the $0.1\mu\text{F}$ capacitor within 0.1 inches of the power pin.
- Connect all external ground pins as tightly as possible, preferably with a large ground plane under the package.
- Layout channel connections to reduce mutual trace inductance.
- Minimize all trace lengths to reduce series inductances. If routing across a board, place device such that longer traces are at the inputs rather than the outputs. If using multiple, low-impedance DC-coupled outputs, special layout techniques may be employed to help dissipate heat.

If a multilayer board is used, a large ground plane directly under the device helps reduce package case temperature.

For dual-layer boards, an extended plane can be used.

Worst-case additional die power due to DC loading can be estimated at $(V_{CC}^2/4R_{load})$ per output channel. This assumes a constant DC output voltage of V_{CC}^2 . For 5V V_{CC} with a dual DC video load, add $25/(4 \cdot 75) = 83\text{mW}$, per channel.

Typical Application

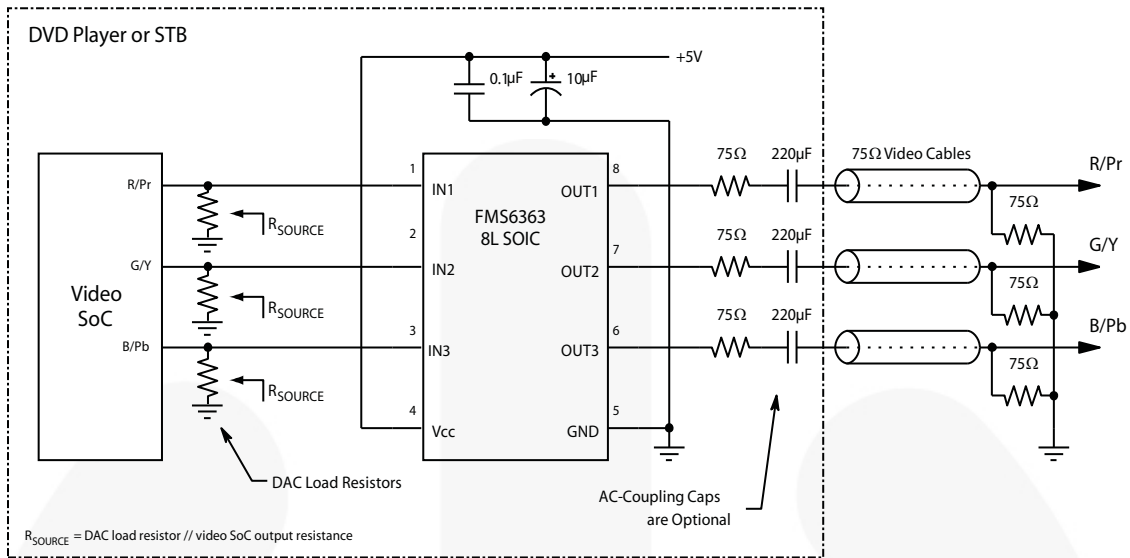


Figure 16. Typical Application Diagram

Physical Dimensions

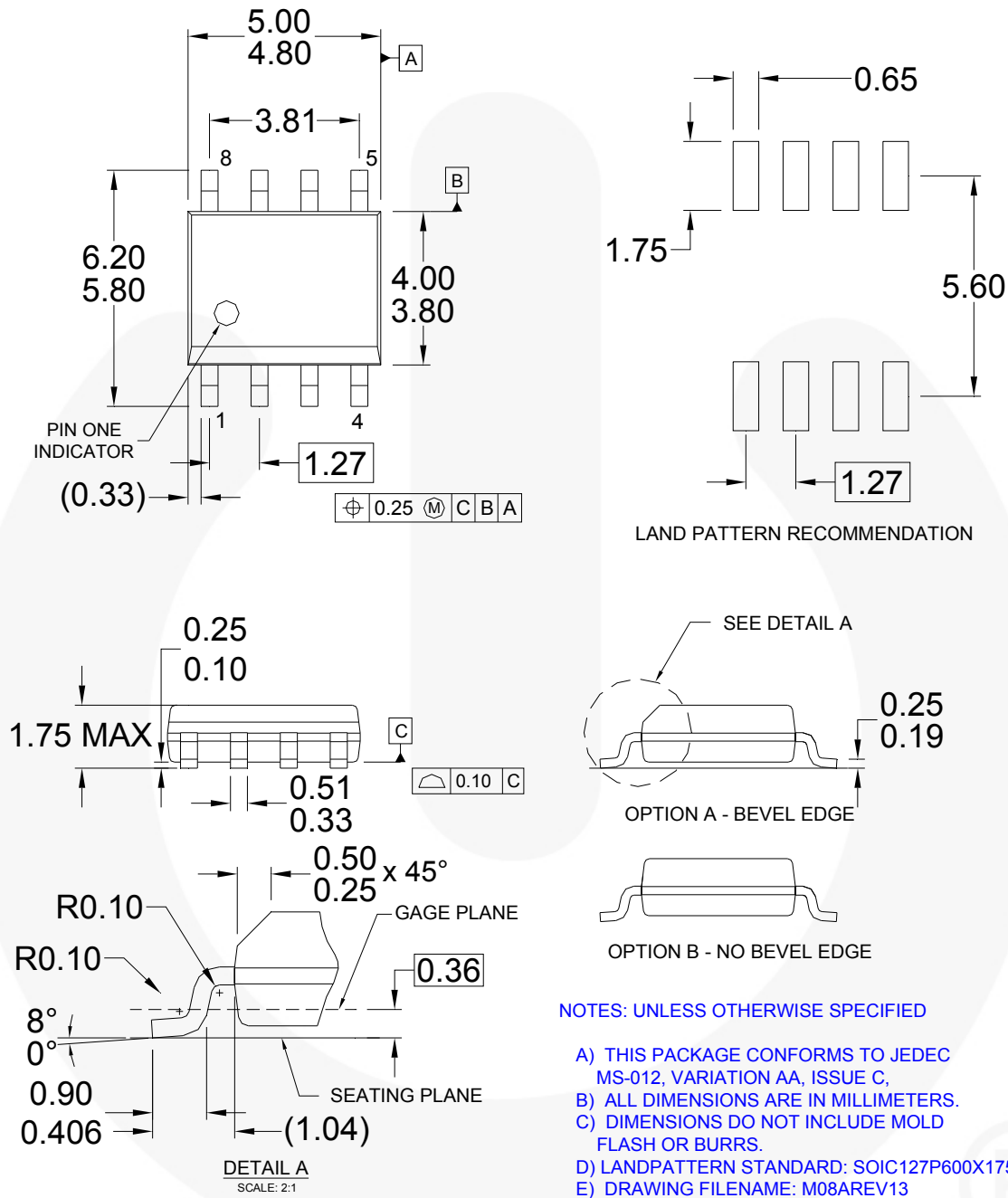


Figure 17. 8-Lead, Small Outline Integrated Circuit (SOIC) Package

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